

B3 13. (amended) The photoresist of claim 1 wherein the heteroalicyclic group fused to the polymer backbone is not an anhydride or lactone.

23. (amended) The photoresist of claim 1 wherein the polymer is a tetrapolymer or a pentapolymer.

B4 24. (amended) The photoresist of claim 1 wherein the polymer is completely free of aromatic groups.

35. (amended) A method of forming a positive photoresist relief image, comprising:

- B5
- (a) applying a coating layer of a photoresist of claim 1 on a substrate; and
 - (b) exposing and developing the photoresist layer to yield a relief image.

B6 41. (amended) An article of manufacture comprising a microelectronic wafer substrate or flat panel display substrate having coated thereon a layer of the photoresist composition of claim 1.

REMARKS

Applicants file herewith a continuation application. The specification has been amended to include the priority claim for the application. For the sole purpose of reducing initial filing fees, claims 6, 7, 9-12, 14-22, 28-34, 36-40, and 42-45 have been cancelled without prejudice, and claims 4, 5, 8, 13, 23, 24, 35 and 41 have been amended. No new matter has been added by virtue of the amendments.

An Information Disclosure Statement will be submitted under separate cover.